

WHAT IS CLAIMED IS:

1. A storage device unit comprising:
a storage device containing a recording medium in a housing; and
a heat radiation device attached to the storage device outside the housing.

2. The storage device unit according to claim 1, wherein said heat radiation device includes:

a base member having a thermal conductivity and contacting the storage device; and

a fin member having a thermal conductivity and contacting the base member.

3. The storage device unit according to claim 2, wherein a guide surface is defined on at least one of the base member and the fin member, the guide surface contacting a predetermined guide fixed within an enclosure, enclosing the storage device, the base member and the fin member, when the guide surface guides movement of the storage device with respect to the enclosure.

4. The storage device unit according to claim 1, wherein the heat radiation device includes:

a base member having a thermal conductivity and contacting the storage device; and

a fin extending from a back surface of the base member.

5. The storage device unit according to claim 4, wherein a guide surface is defined on the base member, the guide surface contacting a predetermined guide fixed within an enclosure, enclosing the storage device, the base member and the fin, when

the guide surface guides movement of the storage device with respect to the enclosure.

6. The storage device unit according to claim 1, wherein the heat radiation device includes:

a base member having a thermal conductivity and contacting the storage device;

a heat pipe contacting the base member; and

a fin having a thermal conductivity and connected to the heat pipe.

7. The storage device unit according to claim 7, wherein a guide surface is defined on the base member, the guide surface contacting a predetermined guide fixed within an enclosure, enclosing the storage device, the base member and the fin, when the guide surface guides movement of the storage device with respect to the enclosure.

8. The storage device unit according to claim 2, wherein a thermally-conductive sheet made of a non-silicon material is interposed between the storage device and the base member.

9. A cooling device comprising:

an enclosure defining a space containing an electronic component;

a thermally-conductive base member contained in the enclosure and defining a surface for receiving the electronic component;

a fin member having a thermal conductivity and contacting the base member;

a guide stationarily located in the enclosure; and

a guide surface defined on at least one of the base member and the fin member, the guide surface being received on the guide to guide movement of the base member with respect to the space of the enclosure.

10. The cooling device according to claim 9, further comprising a stop restraining the movement of the base member in the enclosure.

11. The cooling device according to claim 9, further comprising a fan positioned relative to the base member within the enclosure.

12. The cooling device according to claim 9, wherein the enclosure is an enclosure for an electronic apparatus utilizing the electronic component.

13. A cooling device comprising:

an enclosure defining a space containing an electronic component;

a thermally-conductive base member contained in the enclosure and defining a surface for receiving the electronic component;

a fin extending from a back surface of the base member;

a guide stationarily located in the enclosure; and

a guide surface defined on the base member, the guide surface being received on the guide to guide movement of the base member with respect to the space of the enclosure.

14. The cooling device according to claim 13, further comprising a stop restraining the movement of the base member

in the enclosure.

15. The cooling device according to claim 13, further comprising a fan positioned relative to the base member within the enclosure.

16. The cooling device according to claim 13, wherein the enclosure is an enclosure for an electronic apparatus utilizing the electronic component.

17. A cooling device comprising:

an enclosure defining a space containing an electronic component;

a thermally-conductive base member contained in the enclosure and defining a surface for receiving the electronic component;

a heat pipe contacting the base member;

a fin having a thermal conductivity and connected to the heat pipe;

a guide stationarily located in the enclosure; and

a guide surface defined on the base member, the guide surface being received on the guide to guide movement of the base member with respect to the space of the enclosure.

18. The cooling device according to claim 17, further comprising a stop restraining the movement of the base member in the enclosure.

19. The cooling device according to claim 17, further comprising a fan positioned relative to the base member within the enclosure.

20. A storage device unit comprising:
a storage device;
an enclosure enclosing the storage device; and
a thermally-conductive member made of a non-silicon material and interposed between the storage device and the enclosure.